



Description

JMT N-channel Enhancement Mode Power MOSFET

Features

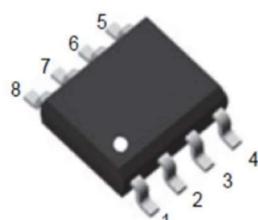
- 40V, 15A
 $R_{DS(ON)} < 9m\Omega$ @ $V_{GS} = 10V$
 $R_{DS(ON)} < 14m\Omega$ @ $V_{GS} = 4.5V$
- Lead free and Green Device Available
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead free product is acquired

Application

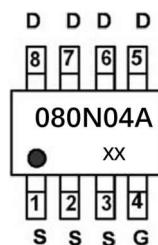
- Load Switch
- PWM Application
- Power management



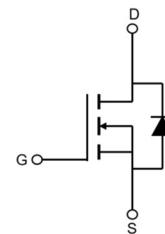
100% UIS TESTED!
100% ΔV_{ds} TESTED!



SOP-8 top view



Marking and pin Assignment



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
080N04A	JMTP080N04A	TAPING	SOP-8	13inch	4000	48000

Absolute Maximum Ratings ($T_c=25^\circ C$ unless otherwise specified)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		40	V
V_{GSS}	Gate-Source Voltage		± 20	V
I_D	Continuous Drain Current	$T_A = 25^\circ C$	15	A
		$T_A = 100^\circ C$	10	A
I_{DM}	Pulsed Drain Current ^{note1}		60	A
E_{AS}	Single Pulsed Avalanche Energy ^{note2}		81	mJ
P_D	Power Dissipation	$T_A = 25^\circ C$	4	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		31.7	$^\circ C/W$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	$^\circ C$

**Electrical Characteristics** ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	40	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=40\text{V}$, $V_{GS}=0\text{V}$,	-	-	1.0	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0\text{V}$, $V_{GS}= \pm 20\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	1.1	1.5	2.5	V
$R_{DS(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{GS}=10\text{V}$, $I_D=15\text{A}$	-	7	9	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$, $I_D=10\text{A}$	-	10.4	14	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=20\text{V}$, $V_{GS}=0\text{V}$, $f=1.0\text{MHz}$	-	2400	-	pF
C_{oss}	Output Capacitance		-	192	-	pF
C_{rss}	Reverse Transfer Capacitance		-	165	-	pF
Q_g	Total Gate Charge	$V_{DS}=20\text{V}$, $I_D=15\text{A}$, $V_{GS}=10\text{V}$	-	37	-	nC
Q_{gs}	Gate-Source Charge		-	6	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	7	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=20\text{V}$, $I_D=10\text{A}$, $R_L=1\Omega$, $R_{\text{GEN}}=3\Omega$, $V_{GS}=10\text{V}$	-	12	-	ns
t_r	Turn-on Rise Time		-	12	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	38	-	ns
t_f	Turn-off Fall Time		-	9	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current	-	-	15	-	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	60	-	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_S=15\text{A}$	-	-	1.2	V
t_{rr}	Body Diode Reverse Recovery Time	$T_J=25^\circ\text{C}$, $I_F=15\text{A}, dI/dt=100\text{A}/\mu\text{s}$	-	22	-	ns
Q_{rr}	Body Diode Reverse Recovery Charge		-	11	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: $T_J=25^\circ\text{C}$, $V_{DD}=20\text{V}$, $V_G=10\text{V}$, $R_G=25\Omega$, $L=0.5\text{mH}$, $I_{AS}=18\text{A}$ 3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

Typical Performance Characteristics

Figure 1: Output Characteristics

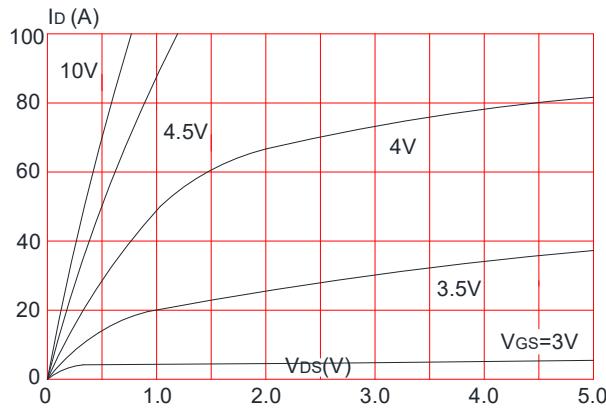


Figure 3: On-resistance vs. Drain Current

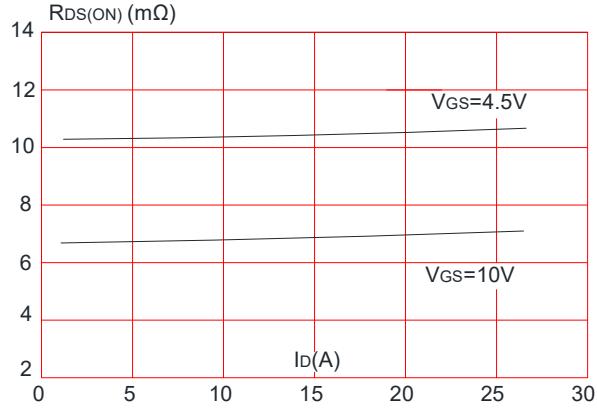


Figure 5: Gate Charge Characteristics

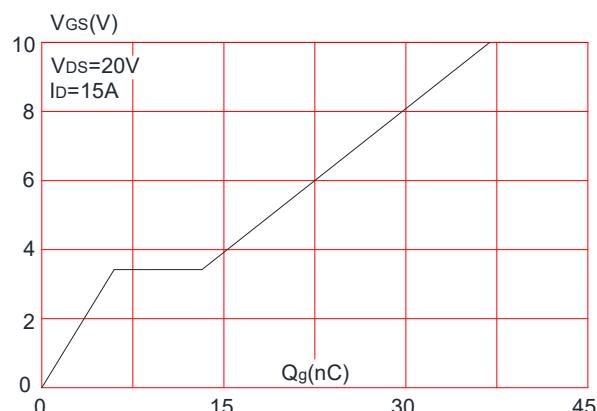


Figure 2: Typical Transfer Characteristics

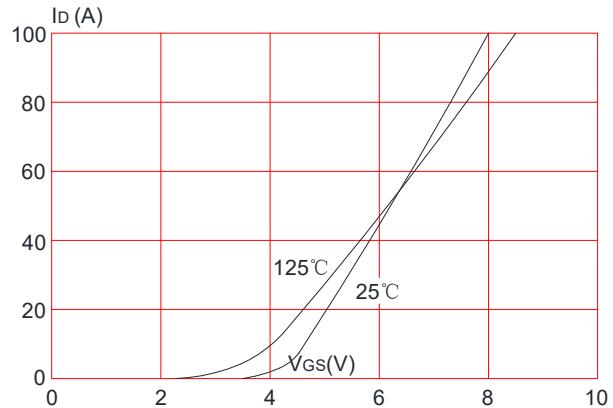


Figure 4: Body Diode Characteristics

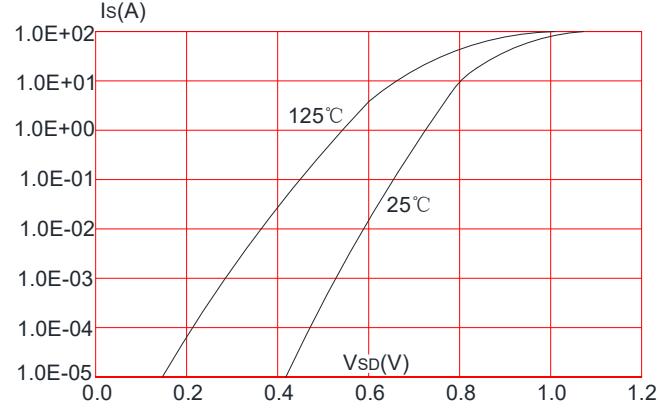


Figure 6: Capacitance Characteristics

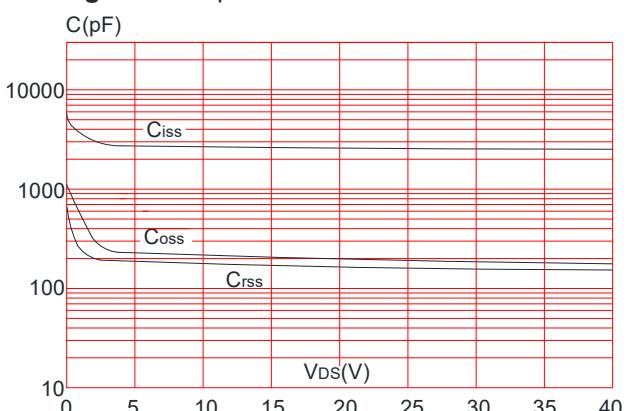


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

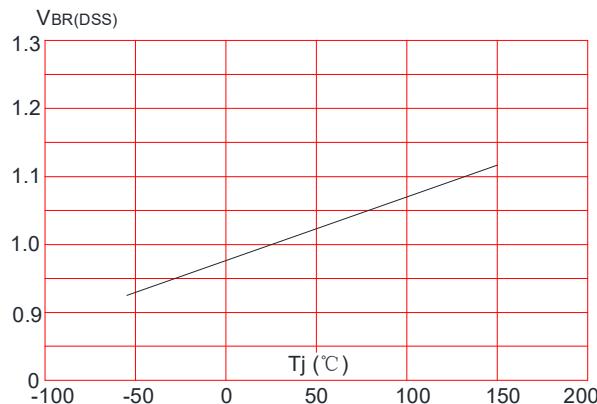


Figure 8: Normalized on Resistance vs. Junction Temperature

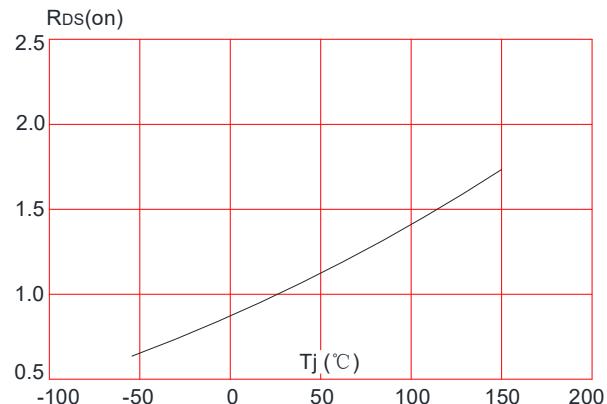


Figure 9: Maximum Safe Operating Area

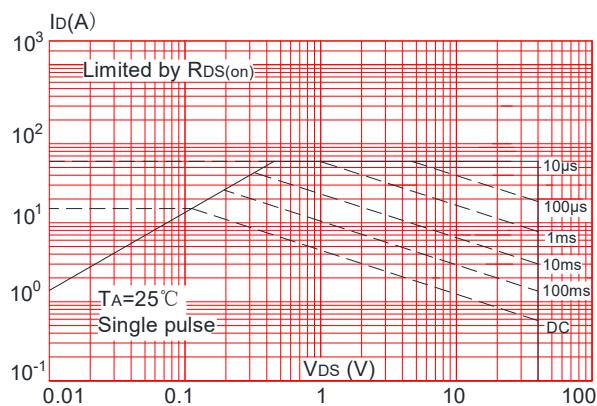


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

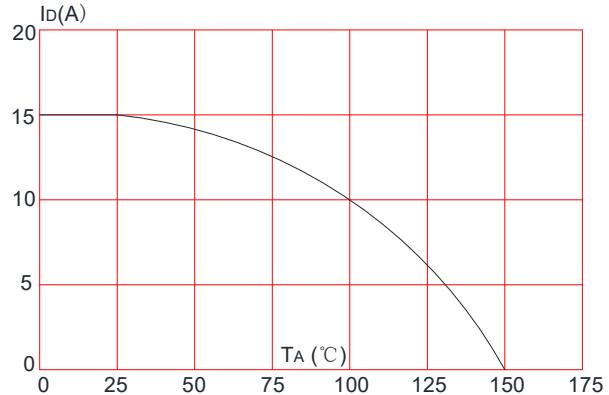
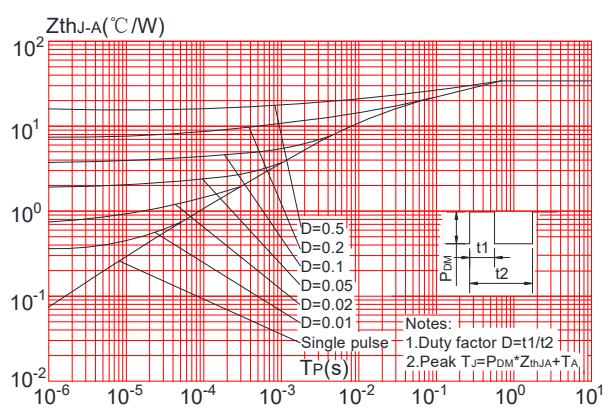


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



Test Circuit



Figure1:Gate Charge Test Circuit & Waveform



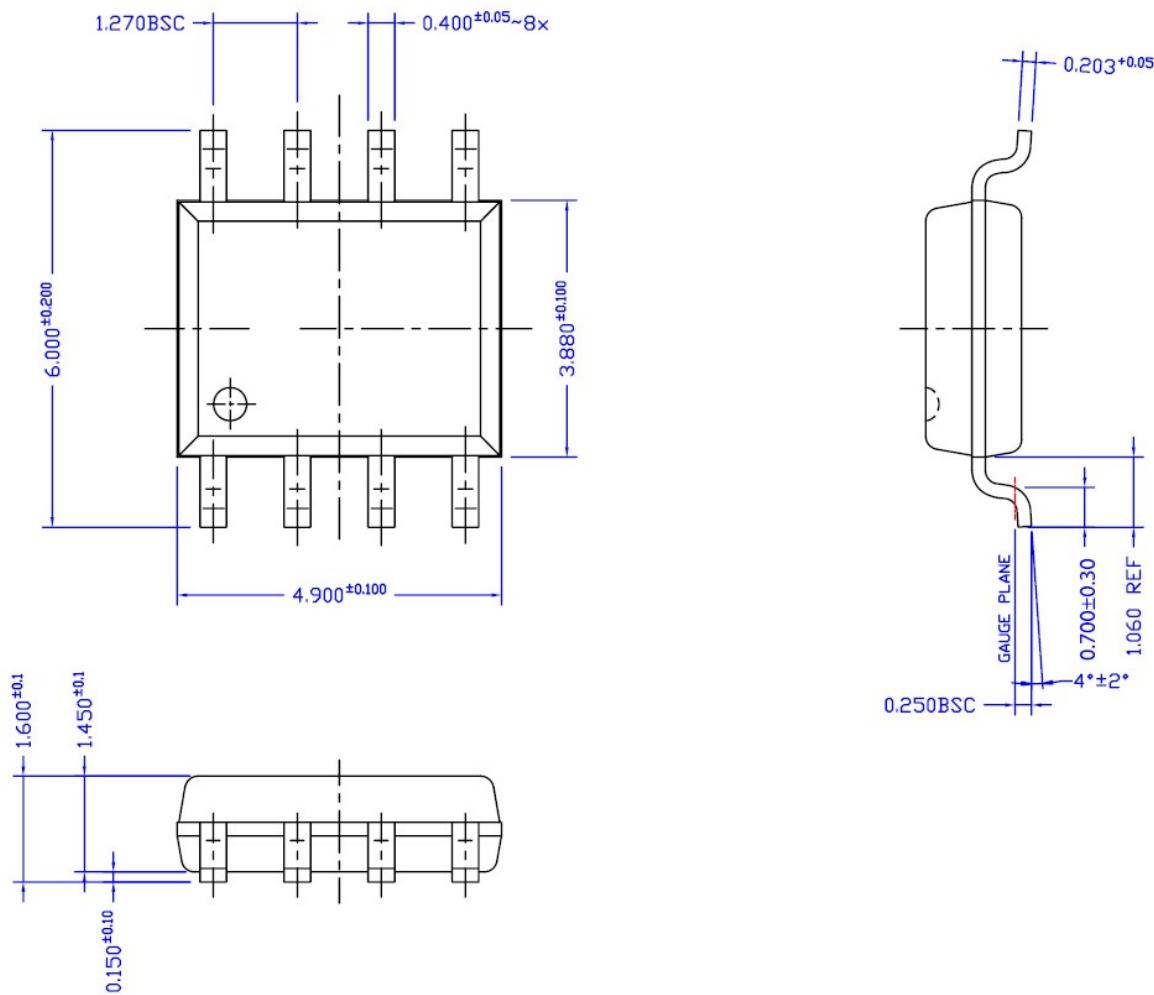
Figure 2: Resistive Switching Test Circuit & Waveforms



Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms



Package Mechanical Data- SOP-8



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